

BS EN 60539-1:2016



BSI Standards Publication

# Directly heated negative temperature coefficient thermistors

Part 1: Generic specification

### **National foreword**

This British Standard is the UK implementation of EN 60539-1:2016. It is identical to IEC 60539-1:2016. It supersedes BS EN 60539-1:2008 which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/40X, Capacitors and resistors for electronic equipment.

A list of organizations represented on this committee can be obtained on request to its secretary.

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July 2016

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English Version

Directly heated negative temperature coefficient thermistors -  
Part 1: Generic specification  
(IEC 60539-1:2016)

Thermistances à coefficient de température négatif à  
chauffage direct - Partie 1: Spécification générique  
(IEC 60539-1:2016)

Direkt geheizte temperaturabhängige Widerstände mit  
negativem Temperaturkoeffizienten -  
Teil 1: Fachgrundspezifikation  
(IEC 60539-1:2016)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels**

## European foreword

The text of document 40/2430/FDIS, future edition 3 of IEC 60539-1, prepared by IEC/TC 40 "Capacitors and resistors for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60539-1:2016.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-03-01
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2019-06-01

This document supersedes EN 60539-1:2008.

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## Endorsement notice

The text of the International Standard IEC 60539-1:2016 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60027-1	NOTE	Harmonized as EN 60027-1.
ISO 80000-1:2009	NOTE	Harmonized as EN ISO 80000-1:2013 (not modified).

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60062	-	Marking codes for resistors and capacitors	EN 60062	-
IEC 60068-1	2013	Environmental testing - Part 1: General and guidance	EN 60068-1	2014
IEC 60068-2-1	-	Environmental testing - Part 2-1: Tests - Test A: Cold	EN 60068-2-1	-
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	-
IEC 60068-2-6	-	Environmental testing - Part 2-6: Tests - Test Fc: Vibration (sinusoidal)	EN 60068-2-6	-
IEC 60068-2-11	-	Basic environmental testing procedures - Part 2-11: Tests - Test Ka: Salt mist	EN 60068-2-11	-
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60068-2-17	-	Basic environmental testing procedures - Part 2-17: Tests - Test Q: Sealing	EN 60068-2-17	-
IEC 60068-2-20	-	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	-
IEC 60068-2-21	-	Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices	EN 60068-2-21	-
IEC 60068-2-27	-	Environmental testing - Part 2-27: Tests - Test Ea and guidance: Shock	EN 60068-2-27	-

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-31	-	Environmental testing - Part 2-31: Tests - Test Ec: Rough handling shocks, primarily for equipment-type specimens	EN 60068-2-31	-
IEC 60068-2-38	-	Environmental testing - Part 2-38: Tests - Test Z/AD: Composite temperature/humidity cyclic test	EN 60068-2-38	-
IEC 60068-2-45 + A1	1980 1993	Basic environmental testing procedures - Part 2-45: Tests - Test XA and guidance: Immersion in cleaning solvents	EN 60068-2-45 + A1	1992 1993
IEC 60068-2-52	-	Environmental testing - Part 2-52: Tests - Test Kb: Salt mist, cyclic (sodium chloride solution)	EN 60068-2-52	-
IEC 60068-2-54	-	Environmental testing - Part 2-54: Tests - Test Ta: Solderability testing of electronic components by the wetting balance method	EN 60068-2-54	-
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60068-2-69	-	Environmental testing - Part 2: Tests - Test Te: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method	EN 60068-2-69	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 60294	-	Measurement of the dimensions of a cylindrical component with axial terminations	EN 60294	-
IEC 60717	-	Method for the determination of the space required by capacitors and resistors with unidirectional terminations	EN 60717	-
IEC 61193-2	-	Quality assessment systems - Part 2: Selection and use of sampling plans for inspection of electronic components and packages	EN 61193-2	-
IEC 61249-2-7	-	Materials for printed boards and other interconnecting structures - Part 2-7: Reinforced base materials, clad and unclad - Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad	EN 61249-2-7	-

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**DIRECTLY HEATED NEGATIVE TEMPERATURE  
COEFFICIENT THERMISTORS –****Part 1: Generic specification**

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 60539-1 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This third edition cancels and replaces the second edition published in 2008. This edition constitutes a technical revision. Tables, figures and references have been revised.

The text of this standard is based on the following documents:

FDIS	Report on voting
40/2430/FDIS	40/2457/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60539 series, published under the general title *Directly heated negative temperature coefficient thermistors*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

# DIRECTLY HEATED NEGATIVE TEMPERATURE COEFFICIENT THERMISTORS –

## Part 1: Generic specification

### 1 Scope

This part of IEC 60539 is applicable to directly heated negative temperature coefficient thermistors, typically made from transition metal oxide materials with semiconducting properties.

It establishes standard terms, inspection procedures and methods of test for use in sectional and detail specifications of electronic components for quality assessment or any other purpose.

### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60062, *Marking codes for resistors and capacitors*

IEC 60068-1:2013, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-1, *Environmental testing – Part 2-1: Tests – Tests A: Cold*

IEC 60068-2-2, *Environmental testing – Part 2-2: Tests – Tests B: Dry heat*

IEC 60068-2-6, *Environmental testing – Part 2-6: Tests – Test Fc: Vibration (sinusoidal)*

IEC 60068-2-11, *Basic environmental testing procedures – Part 2-11: Tests – Test Ka: Salt mist*

IEC 60068-2-14, *Environmental testing – Part 2-14: Tests – Test N: Change of temperature*

IEC 60068-2-17, *Basic environmental testing procedures – Part 2-17: Tests – Test Q: Sealing*

IEC 60068-2-20, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*

IEC 60068-2-21, *Environmental testing – Part 2-21: Tests – Test U: Robustness of terminations and integral mounting devices*

IEC 60068-2-27, *Environmental testing – Part 2-27: Tests – Test Ea and guidance: Shock*

IEC 60068-2-31, *Environmental testing – Part 2-31: Tests – Test Ec: Rough handling shocks, primarily for equipment-type specimens*

IEC 60068-2-38, *Environmental testing – Part 2-38: Tests – Test Z/AD: Composite temperature/humidity cyclic test*